



RE46C803 Carbon Monoxide Detector Companion IC

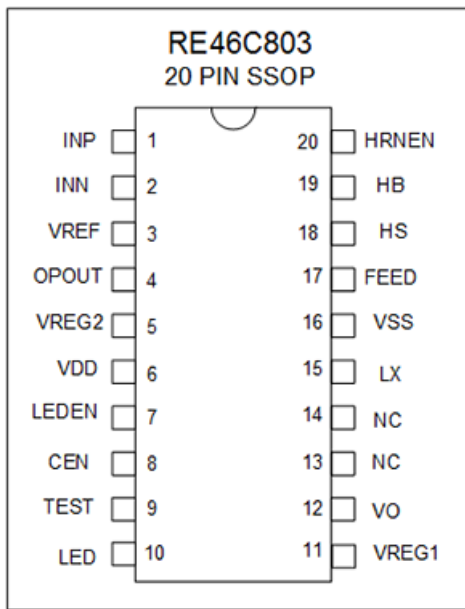
Features

- Low Quiescent Current
- Operation from 3V
- 1.8V Regulated Voltage for CO Detection
- 3.3V Regulated Voltage for Microcontroller Operation in Boost Mode
- 9V Boost Converter
- Horn Driver
- LED Driver
- Internal Operational Amplifier
 - Rail-to-Rail Input and Output
 - 10 KHz Gain Bandwidth Product
 - Unity Gain Stable

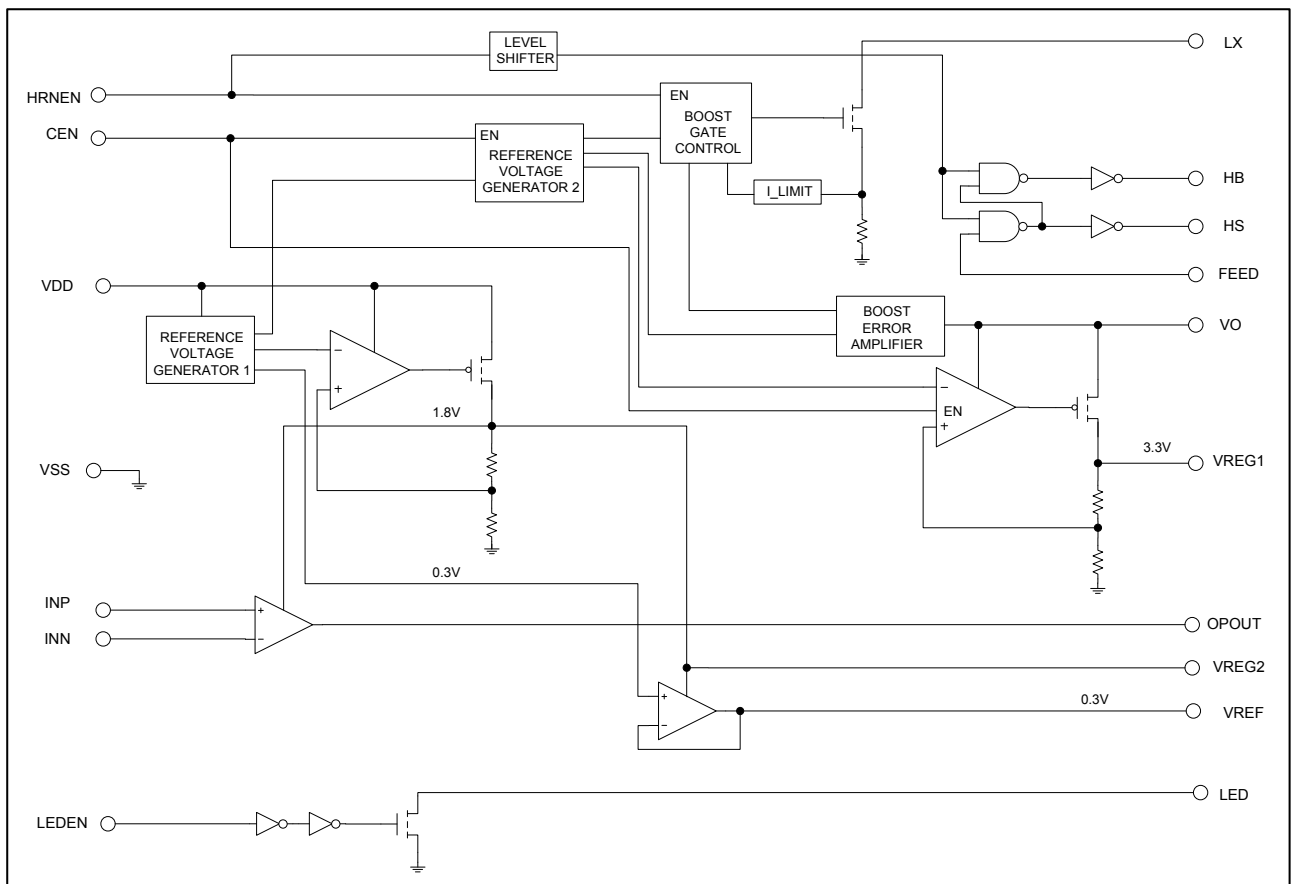
Description

The RE46C803 is a low-voltage, low-power CMOS carbon monoxide detector companion IC. The RE46C803 provides all of the analog, interface, and power regulation functions for a microcontroller-based CO or toxic gas detector. It is intended for use in 3V battery applications. It features a boost converter and horn driver circuit suitable for driving a piezoelectric horn, a 3.3V regulator for microcontroller voltage regulation, an LED driver and an operational amplifier.

Package Type



Functional Block Diagram



Typical Applications

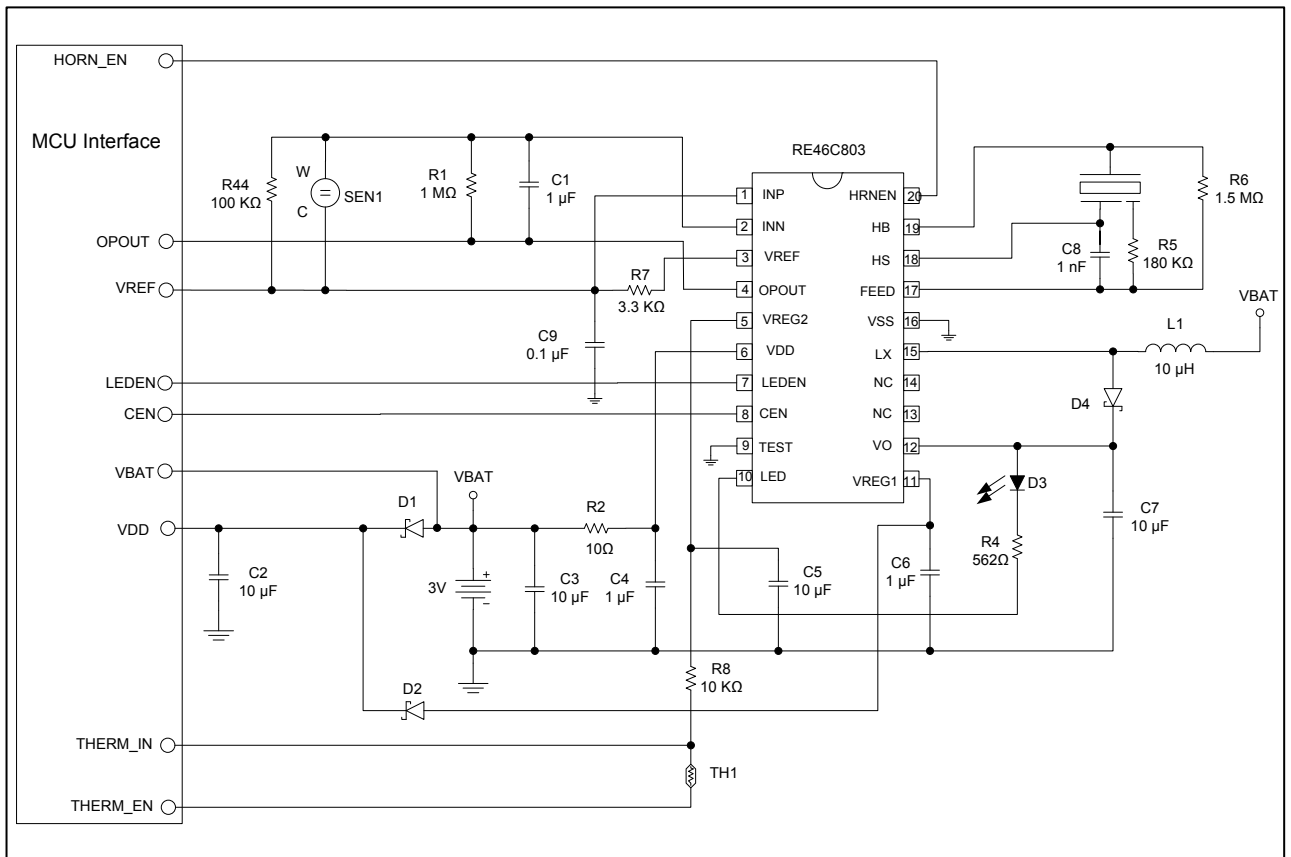


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1. Electrical Characteristics

1.1 Absolute Maximum Ratings

| | |
|--|--|
| V_{DD} | 5V |
| V_O, LX, LED | 15V |
| INP, INN Input Voltage Range | -0.3 to V _{DD} + 0.3V |
| CEN | V _{IN2} = -0.3 to V _O + 0.3V |
| FEED Input Voltage Range | V _{INFD} = -10 to +22V |
| LEDEN, HRNEN Input Voltage Range | -0.3V to 7V |
| Input Current Except FEED | I _{IN} = 10 mA |
| Output Current VREF | I _{REF} = 20 mA |
| Output Current OPOUT | I _{OPO} = 20 mA |
| Sink Current I_{LED} | I _{LED} = 50 mA |
| Output Current I_{HS}, I_{HB} | I _{HS} = I _{HB} = 75 mA |
| Source Current I_{REG1} | I _{REG1} = 50 mA |
| Source Current I_{REG2} | I _{REG2} = 30 mA |
| Operating Temperature | T _A = -10 to +60°C |
| Storage Temperature | T _{STG} = -55 to +125°C |
| Maximum Junction Temperature | T _J = +150°C |

Note: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 1-1. DC Characteristics

Electrical Specifications: Unless otherwise specified, all parameters apply at -10°C ≤ T_A ≤ +60°C, V_{DD} = 3V, V_O = 10V, V_{SS} = 0V, C_{reg1} = 1 μF, C_{reg2} = 10 μF, C_{vo} = 10 μF, (Note 1) (Note 2) (Note 3)

| Parameters | Sym. | Test Pin | Min. | Typ. | Max. | Units | Conditions |
|-------------------------|---------------------|----------|------|------|------|-------|---|
| Supply Voltage | V _{DD} | 6 | 2 | — | 3.6 | V | Operating |
| Standby Supply Current | I _{DDSTBY} | 6 | — | 2.2 | 3.5 | μA | CEN = V _{SS} , Inputs low; No loads, Boost Regulator not running |
| Standby I _{VO} | I _{VOSTBY} | 12 | — | — | 100 | nA | CEN = V _{SS} , Inputs low; No loads, Boost Regulator not running |

| Parameters | Sym. | Test Pin | Min. | Typ. | Max. | Units | Conditions |
|-------------------------|------------|-------------|----------------|------|------|---------|--|
| Quiescent I_{DD} | I_{DDQ} | 6 | — | 33 | 52 | μA | CEN = VDD, Inputs low, No loads, LX = 0.5V |
| Quiescent I_{VO} | I_{VOQ} | 12 | — | — | 69 | μA | CEN = VDD, Inputs low, No loads, LX = 0.5V |
| Input Leakage Low | I_{IL} | 1, 7, 8, 20 | — | — | -100 | nA | INP, LEDEN, CEN, HRNEN Inputs $V_{in} = V_{SS}$ |
| | I_{ILOP} | 2 | — | — | -200 | pA | INN input, $V_{in} = V_{SS}$ |
| | I_{ILF} | 17 | — | -15 | -50 | μA | FEED = -10V, VO = 14V |
| Input Leakage High | I_{IH} | 1, 7, 8, 20 | — | — | 100 | nA | INP, LEDEN, CEN, HRNEN Inputs, $V_{DD} = 3.6V$, $V_{in} = 3.6V$ |
| | I_{IHOP} | 2 | — | — | 200 | pA | INN input, $V_{DD} = 3.6V$, $V_{in} = 3.6V$ |
| | I_{IHF} | 17 | — | 20 | 50 | μA | FEED = +22V, VO = 14V |
| Output Off Leakage High | I_{IHOZ} | 10, 15 | — | — | 1 | μA | LEDEN = VSS, CEN = VSS, VO = LED = LX = 14V |
| Input Voltage Low | V_{IL1} | 7, 8, 20 | — | — | 1 | V | LEDEN, CEN, HRNEN Inputs |
| | V_{ILF} | 17 | — | — | 3 | V | FEED Input |
| Input Voltage High | V_{IH1} | 7, 8, 20 | $V_{DD} - 0.7$ | — | — | V | LEDEN, CEN, HRNEN Inputs |
| | V_{IHF} | 17 | 7 | — | — | V | FEED Input |
| Output Voltage Low | V_{OL1} | 18, 19 | — | 0.3 | 0.5 | V | HS or HB, $I_{out} = 16\text{ mA}$, CEN = VSS, HRNEN = VSS |
| | V_{OL2} | 10 | — | 0.3 | 0.5 | V | LED, $I_{out} = 10\text{ mA}$, CEN = VDD, LEDEN = VDD |
| Boost Output Voltage | V_{OH} | 18, 19 | 9.5 | 9.7 | — | V | HS or HB, $I_{out} = -16\text{ mA}$, CEN = VDD, HRNEN = VDD |
| Output Voltage High | V_{VO} | 12 | 8.2 | 9 | 9.8 | V | CEN = VDD, $I_{out} = 10\text{ mA}$, Boost Regulator running |
| Boost Efficiency | V_{EFF} | — | — | 85 | — | % | CEN=VDD $I_{out}=10\text{mA}$ |
| VREG Voltage | V_{REG1} | 11 | 3.2 | 3.3 | 3.4 | V | $I_{out} < 10\text{ mA}$, CEN = VDD |
| | V_{REG2} | 5 | 1.76 | 1.8 | 1.84 | V | $I_{out} < 5\text{ mA}$ |

| Parameters | Sym. | Test Pin | Min. | Typ. | Max. | Units | Conditions |
|----------------------------------|---------------------------------------|----------|----------------------|------|------------------------|-------|---|
| VREG Load Regulation | V _{REGLD1} | 11 | — | 15 | 25 | mV | I _{out} = 0 to 20 mA, C _{EN} = V _{DD} |
| | V _{REGLD2} | 5 | — | 20 | 40 | mV | I _{out} = 0 to 5 mA |
| Dropout Voltage | V _{DO} | 5 | 0.15 | — | — | V | I _{out} = 5 mA |
| Reference Voltage | V _{REF} | 3 | — | 300 | — | mV | Operating |
| Operational amplifier | | | | | | | |
| Input Offset Voltage | V _{OS} | 1, 2, 4 | -3 | — | 3 | mV | V _{CM} = 0.3V |
| Input Offset Voltage | V _{OS2} | 1, 2, 4 | -1 | — | 1 | mV | T _A = +25°C, V _{CM} = 0.3V |
| Common-Mode Rejection Range | V _{CMR} | 1, 2, 4 | V _{SS} | — | V _{REG2} | V | |
| Common-Mode Rejection Ratio | CMRR | 1, 2, 4 | — | 86 | — | dB | V _{CM} = 0V to V _{REG2} |
| DC Open-Loop Gain (large signal) | AOL | 1, 2, 4 | — | 115 | — | dB | R _L = 50 kΩ, V _{REG2} = 1.8V, V _{CM} = 0.3V, V _{OUT} = 0.3V to V _{REG2} - 0.3V |
| Maximum Output Voltage Swing | V _{OLOP} , V _{OHOP} | 4 | V _{SS} + 10 | — | V _{REG2} - 10 | mV | R _L = 50 kΩ, 0.5V input overdrive |
| Output Short Circuit Current | I _{SC} | 4 | — | 20 | — | mA | |

Note:

1. Wherever a specific VO value is listed under test conditions, the VO is forced externally with the inductor disconnected and the Boost converter is NOT running.
2. Typical values are for design information only
3. The limits shown are 100% tested at +25°C only. Test limits are guard-banded based on temperature characterization to warrant compliance at temperature extremes.

Table 1-2. AC Characteristics

Electrical Specifications: Unless otherwise specified, all parameters apply at -10°C ≤ T_A ≤ +60°C, V_{DD} = 3V, V_O = 10V, V_{SS} = 0V, C_{reg1} = 1 μF, C_{reg2} = 10 μF, C_{vo} = 10 μF, (Note 1) (Note 2) (Note 3)

| Parameters | Sym. | Test Pin | Min. | Typ. | Max. | Units | Conditions |
|-----------------------------------|------|----------|------|------|------|---------|----------------------|
| Operational Amplifier AC Response | | | | | | | |
| Gain Bandwidth Product | GBWP | 1, 2, 4 | — | 10 | — | kHz | |
| Slew Rate | SR | 1, 2, 4 | — | 3 | — | V/ms | |
| Phase margin | PM | 1, 2, 4 | — | 65 | — | ° | G = +1V/V |
| Operational Amplifier Noise | | | | | | | |
| Input Voltage Noise | Eni | 1, 2 | — | 5 | — | μVP - P | f = 0.1 Hz to 10 KHz |
| Input Voltage Noise Density | eni | 1, 2 | — | 170 | — | nV/√Hz | f = 1 KHz |
| Input Current Noise Density | ini | 1, 2 | — | 0.6 | — | fA/√Hz | f = 1 KHz |

Note:

1. Wherever a specific VO value is listed under test conditions, the VO is forced externally with the inductor disconnected and the Boost converter is NOT running.
2. Typical values are for design information only.
3. The limits shown are 100% tested at +25°C only. Test limits are guard-banded based on temperature characterization to warrant compliance at temperature extremes.

Table 1-3. Thermal Specifications

| Parameters | Sym. | Min. | Typ. | Max. | Units | Test Conditions |
|------------------------------|------------------|------|------|------|-------|-----------------|
| Temperature Ranges | | | | | | |
| Operating Temperature Range | T _A | -10 | — | +60 | °C | |
| Storage Temperature Range | T _{STG} | -55 | — | +125 | °C | |
| Thermal Package Resistances | | | | | | |
| Thermal Resistance, 20L-SSOP | θ _{JA} | — | 87 | — | °C/W | |

2. Pin Description

The description of the pins are listed in [Table 2-1](#)

Table 2-1. Pin Function Table

| RE46C803 | Pin Name | Description |
|----------|----------|---|
| SSOP | | |
| 1 | INP | Noninverting input of the operational amplifier. |
| 2 | INN | Inverting input of the operational amplifier. |
| 3 | VREF | Voltage reference for CO biasing and detection circuitry. |
| 4 | OPOUT | Output of the operational amplifier. |
| 5 | VREG2 | Regulated output voltage. Nominal output is 1.8V. |
| 6 | VDD | Connect to a 3V battery through this pin. |
| 7 | LEDEN | Logic input used to enable the LED driver. |
| 8 | CEN | Connect to the microcontroller to start the boost mode. |
| 9 | TEST | Connect to VSS |
| 10 | LED | Open drain NMOS output used to drive a visible LED. |
| 11 | VREG1 | Regulated output voltage. Nominal output is 3.3V. |
| 12 | VO | Regulated output voltage. Nominal output is 9.0V. |
| 13 | NC | Not Connected |
| 14 | NC | Not Connected |
| 15 | LX | Open drain NMOS output used to drive the boost converter inductor. The inductor should be connected from this pin to the positive supply through a low resistance path. |
| 16 | VSS | Connect to the negative supply voltage. |
| 17 | FEED | Usually connected to the feedback electrode of the piezoelectric horn through a resistor. If not used, this pin must be connected to VSS. |
| 18 | HS | HS is a complementary output to HB and connects to the ceramic electrode (M) of the piezoelectric transducer. |
| 19 | HB | This pin is connected to the metal electrode (G) of a piezoelectric transducer. |
| 20 | HRNEN | Logic input to control the operation of the horn driver. |

3. Device Description

3.1 Introduction

The RE46C803 provides the necessary analog functions to build a microcontroller-based CO or toxic gas detector. This includes an operational amplifier and a reference voltage for the electrochemical sensor, a 1.8V regulator that powers the CO detection circuitry or other circuitry such as a thermal sensor, a 3.3V voltage regulator for the microcontroller in alarm, a LED driver, a horn driver and a 9V boost regulator. The RE46C803 provides a simple means for the microcontroller to control the operation of the CO detector and provides the necessary signaling functions during an alarm condition.

3.2 CO Sensor Circuit

The RE46C803 provides a low offset operational amplifier and a voltage reference (VREF) for a two terminal CO or toxic gas sensor. The unity gain stable operational amplifier is powered by the internal regulator VREG2. The operational amplifier provides rail-to-rail inputs and output. The operational amplifier output is monitored by the microcontroller to determine the CO concentration. This uncommitted operational amplifier can be used for other purposes, such as temperature sensing.

3.3 Power Control System

RE46C803 is intended to operate in a 3V battery condition. In standby mode, RE46C803 is powered by the 3V battery through the VDD pin. The voltage on VDD powers the 1.8V voltage regulator VREG2. The 1.8V voltage regulator, in turn, powers the low offset operational amplifier, the reference voltage VREF circuit for CO detection, and other circuits, such as external temperature sensing. In standby mode the boost regulator and the 3.3V voltage regulator is disabled. This keeps the power consumption of RE46C803 to a minimum.

The boost mode is initiated by the microcontroller through the CEN pin. The microcontroller first drives the CEN pin to a high level. This enables the boost regulator and the 3.3V regulator. The microcontroller then drives either HRNEN or LEDEN to a high level. HRNEN asserted high starts sounding the horn alarm. LEDEN asserted high provides load current in battery test or acts as an alarm indicator.

3.4 Boost Regulator

The boost regulator is a fixed off-time boost converter with peak current limiting. The boost regulator is disabled in standby mode and enabled in boost mode. In boost operation, the peak current is nominally 0.8A. The boost regulator provides a nominal 9V on the VO pin. In normal operation, the boost regulator can only be enabled with CEN asserted high. This feature allows VO to reach high boost level before enabling LEDEN or HRNEN.

3.5 Voltage Regulators

There are two voltage regulators in RE46C803.

The low-dropout, low-current 1.8V voltage regulator provides a nominal 1.8V output at the VREG2 pin. The regulator nominal quiescent current is 1 μ A. Internally, the 1.8V regulator provides power to the essential CO detection circuit, the low offset operational amplifier and the reference voltage VREF. Externally, the 1.8V regulator can be used as a reference to the microcontroller, or as the supply for circuit

such as for temperature sensing. The 1.8V regulator will source current up to 5 mA, but the current sinking capability is typically under 1 μ A. The 1.8V regulator is always active and is powered by the battery through the VDD pin.

The 3.3V voltage regulator is only enabled in boost mode with CEN asserted high. It provides a nominal 3.3 V output at the VREG1 pin. The 3.3V regulator can be used to power the microcontroller in boost mode. When enabled, this regulator will source current up to 20 mA, but the current sinking capability is typically under 1 μ A. The 3.3V voltage regulator is powered from the VO pin.

3.6 LED Driver

The LED drive circuit provides power to an LED which can be used as a visual indicator by the system. The LED drive circuit can also be used as part of a battery check function. The CEN must be driven high before enabling LED driver. When LEDEN is asserted high The LED will load the VO output and the microcontroller can monitor the battery operation under load. The load current is set by the resistor in series with the LED.

3.7 Horn Driver

The horn driver drives a standard three terminal piezo horn connected to the pins HB, HS, and FEED. The alarm is sounded by having the microcontroller drive HRNEN pin with required horn modulation pattern. The horn operation requires RE46C803 operate in boost mode. CEN must be driven high before enabling horn driver. This insures there is adequate horn drive capability to achieve the necessary sound pressure levels. The horn will begin to sound before the boost regulator reaches the high boost level.

4. Application Notes

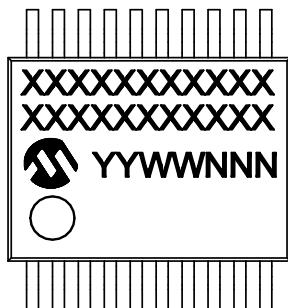
4.1 Boost Regulator

The boost regulator in High-Boost mode (nominal $V_O = 9V$) can draw current pulses of greater than 1A and is, therefore, very sensitive to series resistance. Critical components of this resistance are: the inductor DC resistance, the internal resistance of the battery and the resistance in the connections from the inductor to the battery, from the inductor to the LX pin, from the inductor through the boost capacitor, and from the VSS pin to the battery. In order to function properly under full load at $V_{DD} = 2V$, the total of the inductor and interconnect resistances should not exceed 0.3Ω . The internal battery resistance should be no more than 0.5Ω and a low ESR capacitor of $10\ \mu F$ or more should be connected in parallel with the battery to average the current draw over the boost regulator switching cycle. The Schottky diode and inductor should be specified with a maximum operating current of 1.2A or higher. The boost capacitor should have a low ESR.

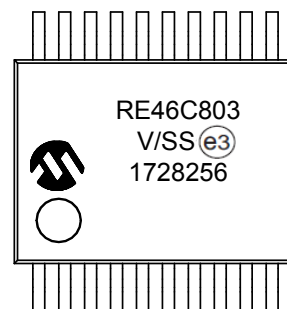
5. Packaging Information

5.1 Marking Information

20-Lead SSOP



Example



Legend:

XX...X Customer-specific information

Y Year code (last digit of calendar year)

YY Year code (last 2 digits of calendar year)

WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

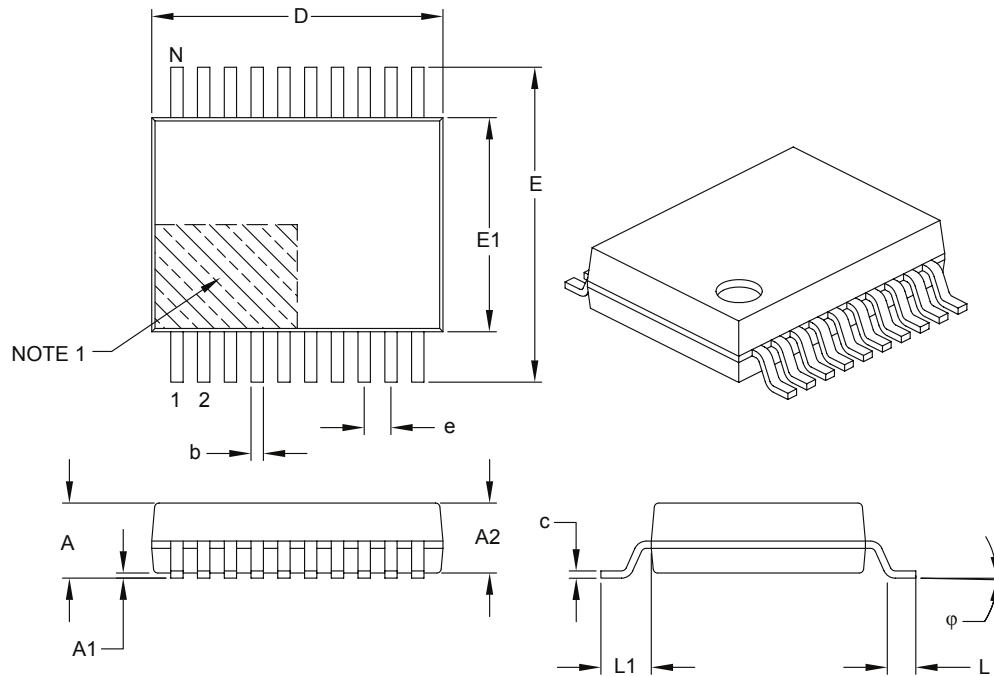
e3 JEDEC® designator for Matte Tin (Sn)

* This package is RoHS compliant. The JEDEC designator (**e3**) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits | Units | MILLIMETERS | | |
|--------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Number of Pins | N | 20 | | |
| Pitch | e | 0.65 BSC | | |
| Overall Height | A | – | – | 2.00 |
| Molded Package Thickness | A2 | 1.65 | 1.75 | 1.85 |
| Standoff | A1 | 0.05 | – | – |
| Overall Width | E | 7.40 | 7.80 | 8.20 |
| Molded Package Width | E1 | 5.00 | 5.30 | 5.60 |
| Overall Length | D | 6.90 | 7.20 | 7.50 |
| Foot Length | L | 0.55 | 0.75 | 0.95 |
| Footprint | L1 | 1.25 REF | | |
| Lead Thickness | c | 0.09 | – | 0.25 |
| Foot Angle | φ | 0° | 4° | 8° |
| Lead Width | b | 0.22 | – | 0.38 |

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

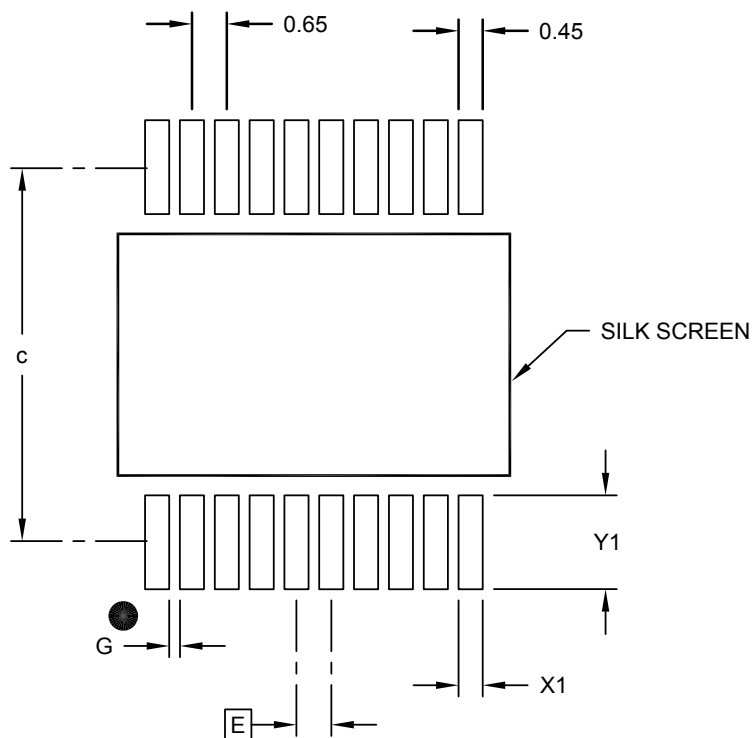
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

20-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|--------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.65 BSC | | |
| Contact Pad Spacing | C | | 7.20 | |
| Contact Pad Width (X20) | X1 | | | 0.45 |
| Contact Pad Length (X20) | Y1 | | | 1.75 |
| Distance Between Pads | G | 0.20 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2072B

6. Revision History

Revision A (August 2017)

Original Release of this Document.

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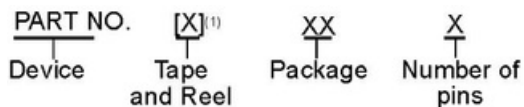
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- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

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Product Identification System

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



| | | |
|---------------------|---|--|
| Device: | RE46C803SS20: CMOS Carbon Monoxide Detector Companion | |
| Tape & Reel Option: | Blank | = Tube |
| | T | = Tape & Reel |
| Package | SS | = Package Plastic Shrink Small Outline |
| Number of pins | 20 | |

Examples:

- RE46C803SS20: 20-pin SSOP package
- RE46C803SS20T: Tape and Reel, 20-pin SSOP package

Note:

1. Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.
2. Small form-factor packaging options may be available. Please check <http://www.microchip.com/packaging> for small-form factor package availability, or contact your local Sales Office.

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